

## COMPOSITION FOR TREATING COPPER OR COPPER ALLOYS

### ABSTRACT OF THE DISCLOSURE

A composition suitable for the treatment of surfaces of copper and copper alloys is disclosed. It comprises, (a) a cupric complex of an azole compound, (b) an organic acid having a boiling point or a decomposition point of 230°C or lower, (c) a difficultly volatile complexing agent, (d) a complexing agent having a complexing power which is weaker than that of the azole compound, and (e) water. The treatment of copper or copper alloys with the composition produces abraded surface with moderate irregularities, thereby ensuring better adhesion of various resists thereto and increased solderability. The composition is particularly useful for the manufacture of printed-wiring boards.